

Ultrafast Diode

80 A, 1000 V

RURG80100

Description

The RURG80100 is an ultrafast diode with low forward voltage drop. This device is intended for use as freewheeling and clamping diodes in a variety of switching power supplies and other power switching applications. It is specially suited for use in switching power supplies and industrial application.

Features

- Ultrafast Recovery, $t_{rr} = 200 \text{ ns}$ (@ $I_F = 80 \text{ A}$)
- Max Forward Voltage, $V_F = 1.9 \text{ V}$ (@ $T_C = 25 \text{ }^\circ\text{C}$)
- 1000 V Reverse Voltage and High Reliability
- Avalanche Energy Rated
- This Device is Pb-Free and is RoHS Compliant

Applications

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

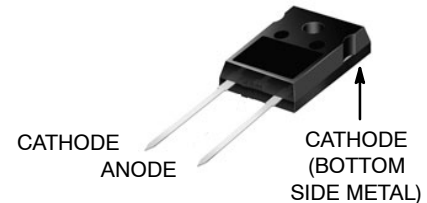
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	1000	V
Working Peak Reverse Voltage	V_{RWM}	1000	V
DC Blocking Voltage	V_R	1000	V
Average Rectified Forward Current ($T_C = 53 \text{ }^\circ\text{C}$)	$I_{F(AV)}$	80	A
Repetitive Peak Surge Current (Square Wave, 20 kHz)	I_{FRM}	160	A
Nonrepetitive Peak Surge Current (Halfwave 1 Phase, 60 Hz)	I_{FSM}	500	A
Maximum Power Dissipation	P_D	180	W
Avalanche Energy (See Figure 7 and Figure 8)	E_{AVL}	50	mJ
Operating and Storage Temperature	T_{STG}, T_J	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



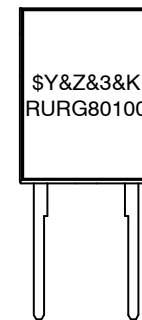
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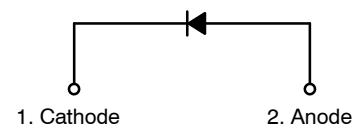


JEDEC STYLE 2 LEAD TO-247
340CL

MARKING DIAGRAM



\$Y = ON Semiconductor Logo
 &Z = Assembly Plant Code
 &3 = Numeric Date Code
 &K = Lot Code
 RURG80100 = Specific Device Code



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

RURG80100

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Package	Brand
RURG80100	TO-247-2L	RURG80100

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_F	Instantaneous Forward Voltage (Pulse Width = 300 μs , Duty Cycle = 2%)	$I_F = 80\text{ A}$			1.9	V
		$I_F = 80\text{ A}$, $T_C = 150^\circ\text{C}$			1.7	V
I_R	Instantaneous Reverse Current	$V_R = 1000\text{ V}$			250	μA
		$V_R = 1000\text{ V}$ $T_C = 150^\circ\text{C}$			2	mA
T_{rr}	Reverse Recovery Time (See Figure 6) Summation of $t_a + t_b$	$I_F = 1\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$			125	ns
		$I_F = 80\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$			200	ns
t_a	Time to Reach Peak Reverse Current (See Figure 6)	$I_F = 80\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$		90		ns
t_b	Time from Peak I_{RM} to Projected Zero Crossing of I_{RM} Based on a Straight Line from Peak I_{RM} Through 25% of I_{RM} (See Figure 6)	$I_F = 80\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$		65		ns
$R_{\theta JC}$	Thermal Resistance Junction to Case				0.83	$^\circ\text{C}/\text{W}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CURVES

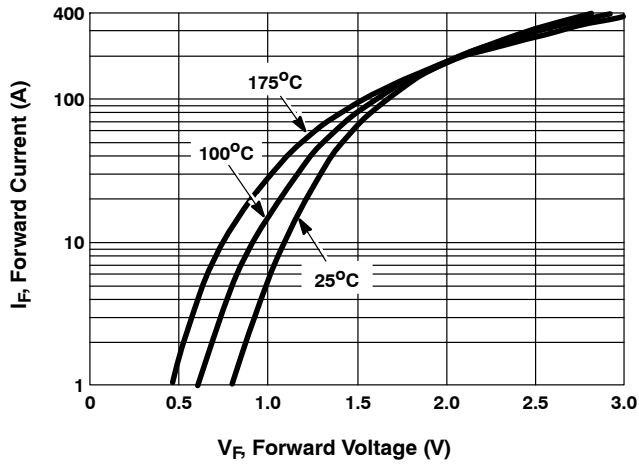


Figure 1. Forward Current vs. Forward Voltage

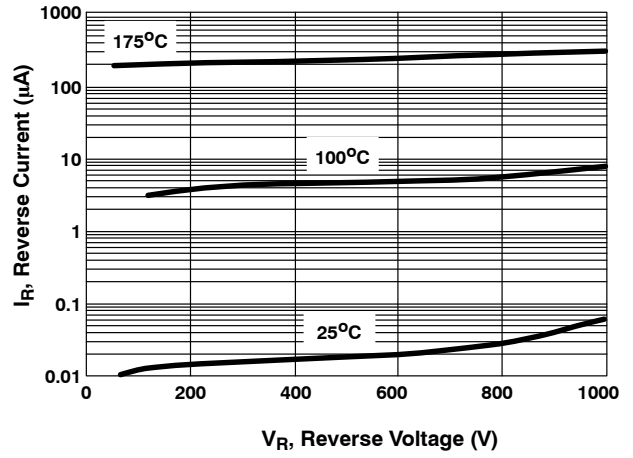


Figure 2. Reverse Current vs. Reverse Voltage

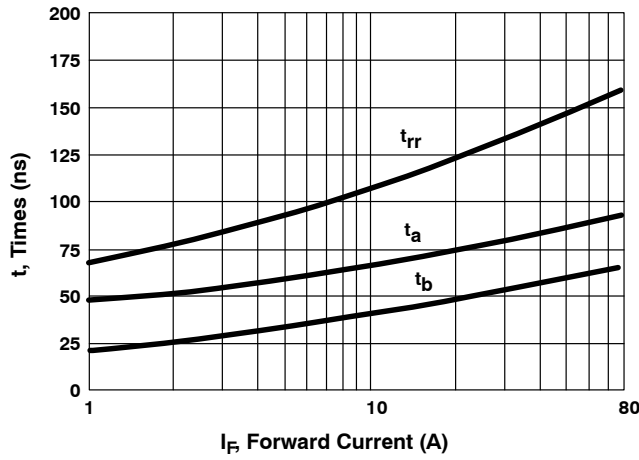


Figure 3. t_{rr} , t_a and t_b Curves vs. Forward Current

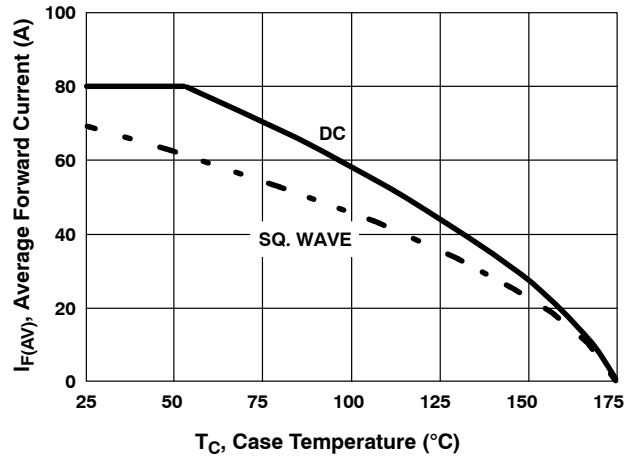


Figure 4. Current Derating Curve

TEST CIRCUITS AND WAVEFORMS

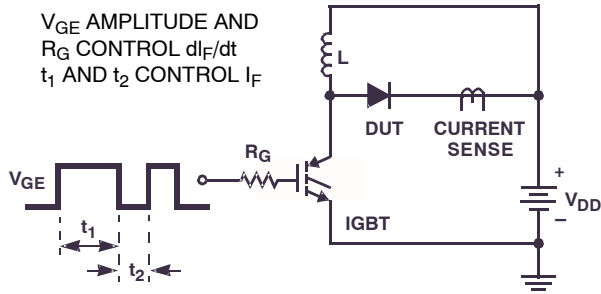


Figure 5. T_{rr} Test Circuit

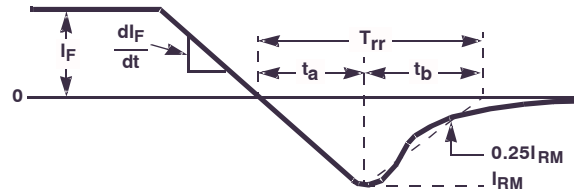


Figure 6. T_{rr} Waveforms and Definitions

$I = 1.6 \text{ A}$
 $L = 40 \text{ mH}$
 $R < 0.1 \Omega$
 $E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$
 $Q_1 = \text{IGBT (} BV_{CES} > DUT V_{R(AVL)} \text{)}$

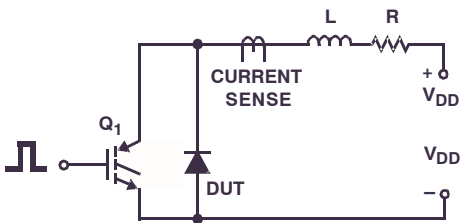


Figure 7. Avalanche Energy Test Circuit

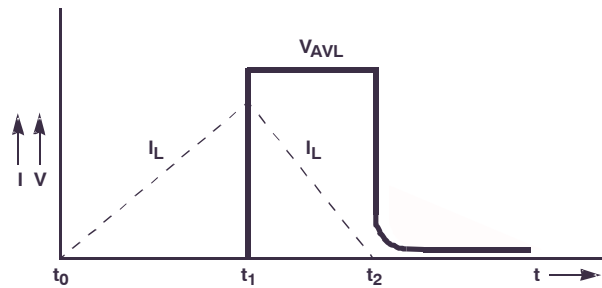


Figure 8. Avalanche Current and Voltage Waveforms

MECHANICAL CASE OUTLINE

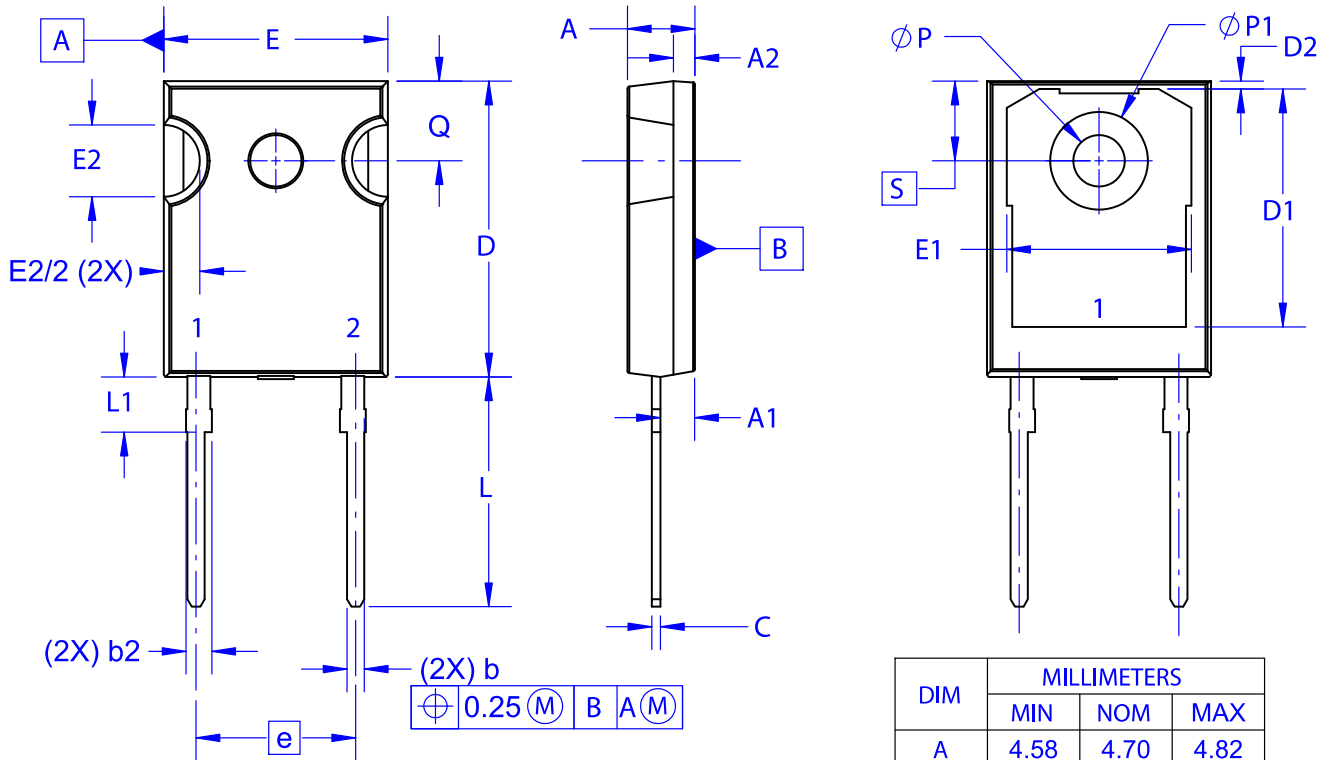
PACKAGE DIMENSIONS

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TO-247-2LD
CASE 340CL
ISSUE A

DATE 03 DEC 2019

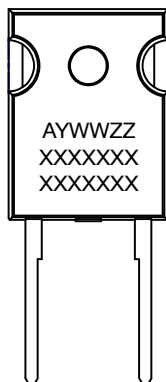


⊕ 0.25 (M) B A (M)

NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.58	4.70	4.82
A1	2.29	2.40	2.66
A2	1.30	1.50	1.70
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
c	0.51	0.61	0.71
D	20.32	20.57	20.82
D1	16.37	16.57	16.77
D2	0.51	0.93	1.35
E	15.37	15.62	15.87
E1	12.81	~	~
E2	4.96	5.08	5.20
e	~	11.12	~
L	15.75	16.00	16.25
L1	3.69	3.81	3.93
∅P	3.51	3.58	3.65
∅P1	6.61	6.73	6.85
Q	5.34	5.46	5.58
S	5.34	5.46	5.58

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